



Final Product Change Notification **Withdrawal**

201903005F01W : Withdrawal: ASEK Grinding/Sawing Transferring to ATKH - NX20P5090UK

Note: This notice is NXP Company Proprietary.

Issue Date: May 13, 2022 **Effective date:** Aug 11, 2022

Here is your personalized notification about a NXP general announcement.

For detailed information we invite you to [view this notification online](#)

Management summary

BE2 (back half of the Assembly process) transferring from ASEK to ATKH (grinding/sawing/marketing and packing).

BE2 will be enabled in ATKH.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input checked="" type="checkbox"/> Other: BE2 process transferring (Grinding/Sawing/Marking/Packing)			

PCN Overview

Description

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2 (back half of the Assembly process).

The flow allows for manufacturing flexibility and helps ensure customer supply.

BE2(back half of the Assembly process) (grinding/sawing/marketing and Packing) will be enabled in ATKH.

There's no change in Form, Fit or Function.

Reason

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2.

The flow allows for manufacturing flexibility and helps ensure customer supply.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Not Applicable

Production

Planned first shipment

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jun 12, 2022.

Remarks

Withdraw the FPCN 201903005F01, the BE2 tranfer of NX20P5090 was cancelled.

Withdrawal Information

NXP decided to stop the NX20P5090 BE2 expansion because the current ASEK has enough capacity to support customer demands.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Wenfeng Zhao
Position BL SIP Quality Engineer
e-mail address wenfeng.zhao@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications. You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization. This message has been automatically distributed. Please do not reply .

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006- 2022 NXP Semiconductors. All rights reserved.

Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	New Orderable Part#	12NC New	Product Type New	Product Description New	Product Line	Notes
NX20P5090UKAZ	935305697041	NX20P5090UK	5A OVP switch for typeC			RFS	No					BLC4	